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### Multi-layer ceramic chip capacitors

### MCH03 (0603 size, chip capacitor)

#### Features

- 1) Small size (0.6 x 0.3 x 0.3 mm) makes it perfect for lightweight portable devices.
- 2) Comes packed either in tape to enable automatic mounting.
- 3) Precise uniformity of shape and dimensions facilitates highly efficient automatic mounting.
- 4) Barrier layer and end terminations to improve solderability.

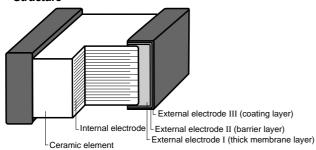
#### 0.6±0.03 0.6±0.03 0.00

0.3±0.03

●External dimensions (Units: mm)

0.1Min. 0.17Min.





#### Product designation

or roudet designation								
			Code F	Product thickness	Packag	ging specifications	Reel	Basic ordening unit (pcs.)
			K	0.3mm	Paper tape	(width 8 mm, pitch 2 mm)	φ180mm (7in.)	15,000
			Reel (¢1	80, ¢330mm) :	compatible	with EIAJ ET-7200A		
Part No.	Part No. Packaging style							
		. — ——	. ———		<b>=</b>			
	0    3	2  F  N	1    1    2	7	K			
MCH	<u> </u>			ر کا د				
			. ——			_		
Rated voltage Capacitance-temperature characteristics			Nominal Capacitance tolerance					
Code Voltage	Code Co	de Operating temperature (°C)	Temp. coefficient or percent change	capacitance	Code	tolerance		
<b>2</b> 25V	A CG(	0G) -55~+125	0±30ppm/°C		<b>C</b> ±0	0.25pF (0.5 ~ 5pF)		
<b>3</b> 16V	CN F	-55~+125	±15%		<b>D</b> ±0	0.5pF (5.1 ~ 10pF)		
<b>5</b> 50V	E		±10%	3-digit designation	J ±	5% (11pF or more)		
	(X7		(±15%)	according to IEC	lκ	± 10%		
	FN F	20 100	+30%,-80%	1				
	(Y	V) (-30~+85)	(+22%,-82%)	J	<b>Z</b> +	80%, –20%		

<sup>\*</sup>The design and specifications are subject to change without prior notice. Before ordering or using, please check the latest technical specification.

#### Capacitance range

For thermal compensation

For thermal compensation					
Part n	MCH03				
Capacitance (pF)	Temperature characteristics  Rated voltage	(CG) (C0G)			
	Tolerance (V)	25V			
0.5 0.75 1					
1.1 1.2 1.3					
1.5 1.6 1.8					
2 2.2 2.4	C ( ± 0.25pF)				
2.7 3 3.3					
3.6 3.9 4					
4.3 4.7 5					
5.1 5.6 6					
6.2 6.8 7	D ( ± 0.5pF)				
7.5 8 8.2	( = 0.0p. )				
9 9.1 10					

Part n	MCH03	
Capacitance (pF)	Temperature characteristics	A (CG) (C0G)
Capacitance (pr)	Rated voltage (V) Tolerance	25V
11		
12		
13		
15		
16		
18		
20		
22	14 . =04)	
24	J ( ± 5%)	
27		
30		
33		
36		
39		
43		
47		

Product thickness (mm) 0.3±0.03

#### High dielectric constant

night delectric constant				
Part n	umber	MCH03		
Conscitones (nF)	Temperature characteristics	CN (R) (B) (X7R)	FN (F) (Y5V)	
Capacitance (pF)	Rated voltage (V)	25V	25V	
	Tolerance	K ( ±10%)	Z ( +80, -20%)	
100	_			
150				
200				
330				
470				
680				
1,000				
1,500				
2,200				
4,700				
10,000				

Product thickness (mm) 0.3±0.03

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#### Characteristics

Class 1 (For thermal compensation)

	Temperature characteristics		Test methods/conditions	
Item		A (CG) (C0G)	(based on JIS C 5102)	
Operating temp	perature	−55°C ~ 125°C		
Nominal capacitance (C)		Must be within the specified tolerance range.	Based on paragraph 7.8 and paragraph 9 Measured at room temperature and standard humidity,	
Dissipation factor (tanδ)		100/(400+20C)% or less: Less than 30 pF 0.1% or less : 30 pF or larger	1000pF or less Measurement frequency : 1 ± 0.1MHz  Measurement voltage : 1 ± 0.1Vrms.  Over 1000pF Measurement frequency : 1 ± 0.1kHz  Measurement voltage : 1 ± 0.1Vrms.	
Insulation resis	tance (IR)	10,000M $\Omega$ or 500M $\Omega \cdot \mu F,$ whichever is smaller	Based on paragraph 7.6 Measurement is made after rated voltage is applied for 60 $\pm$ 5s	
Withstanding v	oltage	The insulation must not be damaged.	Based on paragraph 7.1 Apply 300% of the rated voltage for 1 to 5s then measure.	
Temperature cl	haracteristics	Within $0 \pm 30 \text{ppm/}^{\circ}\text{C}$	The temperature coefficients in table 12, paragraph 7.12 are calculated at 20°C and high temperature.	
Terminal adherence		No detachment or signs of detachment.	Based on paragraph 8.11. 2. Apply 2N for 10 ± 1s in the direction indicated by the arrow.  Pressure (2N) Test board Capacitor	
	Appearance	There must be no mechanical damage.	Chip is mounted to a board in the manner	
Resistance to vibration	Rate of capacitance change	Must be within initial tolerance.	shown on the right, subjected to vibration (type A in paragraph 8.2), and measured	
	Dissipation factor (tanδ)	Must satisfy initial specified value.	24 ± 2 hrs. later.	
Solderability		At least 3/4 of the surface of the two terminals must be covered with new solder.	Based on paragraph 8.13 Soldering temperature: 235 ± 5°C Soldering time : 2 ± 0.5s	
	Appearance	There must be no mechanical damage.		
	Rate of capacitance change	$\pm$ 2.5% or $\pm$ 0.25 pF, whichever is larger.	Based on paragraph 8.14.  Soldering temperature: 260 ± 5°C  Soldering time : 5 ± 0.5s  Preheating : 150 ± 10°C for 1 to 2 min	
Resistance to soldering	Dissipation factor (tanδ)	Must satisfy initial specified value.		
heat	Insulation resistance	10,000M $\Omega$ or 500M $\Omega \cdot \mu F$ , whichever is smaller		
	Withstanding voltage	The insulation must not be damaged.		
	Appearance	There must be no mechanical damage.		
_	Rate of capacitance change	$\pm$ 2.5% or $\pm$ 0.25 pF, whichever is larger.	Based on paragraph 9.3	
Temperature cycling	Dissipation factor (tanδ)	Must satisfy initial specified value.	Number of cycles : 5	
	Insulation resistance	10,000M $\Omega$ or 500M $\Omega \cdot \mu F,$ whichever is smaller	Capacitance measured after 24 ± 2 hrs.	
Humidity load test	Appearance	There must be no mechanical damage.	Based on paragraph 9.9	
	Rate of capacitance change	$\pm$ 7.5% or $\pm$ 0.75 pF, whichever is larger.	Test temperature: 40 ± 2°C Relative humidity: 90% to 95%	
	Dissipation factor (tanδ)	0.5% or less	Applied voltage : rated voltage	
	Insulation resistance	500M $\Omega$ or $25M\Omega \cdot \mu F,$ whichever is smaller	Test time : 500 to 524 hrs. Capacitance measured after 24 ± 2 hrs.	
High- temperature load test	Appearance	There must be no mechanical damage.	Based on paragraph 9.10	
	Rate of capacitance change	$\pm$ 3.0% or $\pm$ 0.3 pF, whichever is larger.	Test temperature: Max. operating temp.	
	Dissipation factor (tanδ)	0.3% or less	Applied voltage : rated voltage × 200% Test time : 1,000 to 1,048 hrs.	
	Insulation resistance	1,000M $\Omega$ or $50M\Omega \cdot \mu F,$ whichever is smaller	Capacitance measured after 24 $\pm$ 2 hrs.	

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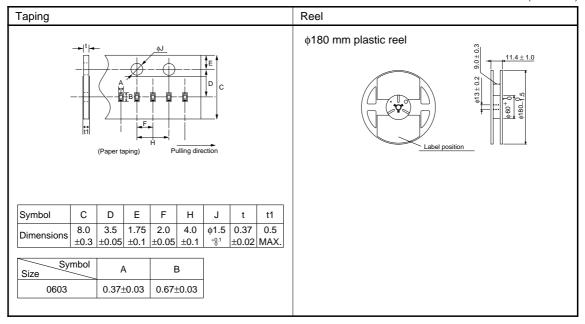
Class 2 (High dielectric constant)

>1400 Z (1 light 410	lectric constant)				
Temperature characteristics		CN (R) (B) (X7R)	FN (F) (Y5V)	Test methods/conditions (based on JIS C 5102)	
Operating temperature		−55°C ~ +125°C	−30°C ~ +85°C		
Nominal capaci	itance (C)	Must be within the spe	cified tolerance range.	Based on paragraph 7.8  Measured at room temperature and standard humidity.	
Dissipation factor (tanδ)		2.5% or less (when rated voltage is 16V: 3.5% or less) (when rated voltage is 16V: 7.5% or less)		Measurement frequency: 1 ± 0.1 kHz	
Insulation resistance (IR)		10,000MΩ or 500MΩ · μF, whichever is smaller		Based on paragraph 7.6 Measurement is made after rated voltage is applied for $60 \pm 5s$ .	
Withstanding voltage		The insulation must not be damaged.		Based on paragraph 7.1 Apply 250% of the rated voltage for 1 to 5s then measure	
Temperature ch	haracteristics	Within ± 15%	+ 22, + 82%	The temperature coefficients in paragraph 7.12, table 8, condition B, are based on measurements carried out at 20°C, with no voltage applied.	
Terminal adherence		No detachment or signs of detachment		Based on paragraph 8. 11. 2.  Apply 2N for 10 ± 1s in the direction indicated by the arrow.  Pressure (2N) Test board Capacitor	
	Appearance	There must be no mechanical damage.		Chip is mounted to a board in the	
Resistance to vibration	Rate of capacitance change	Must be within initial tolerance.		manner shown on the right, subjected to vibration (type A in paragraph 8.2), and measured 48 ± 4 hrs. later.	
	Dissipation factor (tanδ)	Must satisfy initia			
Solderability		At least 3/4 of the surface of the two terminals must be covered with new solder.		Based on paragraph 8. 13 Soldering temperature : 235 $\pm$ 5°C Soldering time : 2 $\pm$ 0.5s	
	Appearance	There must be no mechanical damage.		Based on paragraph 8. 14.  Soldering temperature : 260 ± 5°C  Soldering time : 5 ± 0.5s  Preheating : 150 ± 10°C for  1 to 2 min.	
	Rate of capacitance change	Within ± 5.0% Within ± 20.0%			
Resistance to soldering	Dissipation factor (tanδ)	Must satisfy initial specified value.			
heat	Insulation resistance	10,000Μ $\Omega$ or 500Μ $\Omega$ · $\mu$ F, whichever is smaller			
	Withstanding voltage	The insulation mus			
	Appearance	There must be no m	nechanical damage.		
Temperature	Rate of capacitance change	Within ± 7.5% Within ± 20.0%		Based on paragraph 9.3	
cycling	Dissipation factor (tanδ)	Must satisfy initial specified value.		Number of cycles : 5 Capacitance measured after 48 ± 4 h	
	Insulation resistance	10,000MΩ or 500MΩ $\cdot$ μF, whichever is smaller			
Humidity load test	Appearance	There must be no m	Based on paragraph 9.9		
	Rate of capacitance change	± 12.5% or less	Within ± 30.0%	Test temperature: 40 ± 2°C	
	Dissipation factor (tanδ)	7.5% or less (when rated voltage is 16V: 10.0%)		Relative humidity: 90% to 95% Applied voltage : rated voltage Test time : 500 to 524 hrs. Capacitance measured after 48 ± 4 hrs	
	Insulation resistance	500M $\Omega$ or 25M $\Omega$ · μF, whichever is smaller			
High- temperature load test	Appearance	There must be no mechanical damage.			
	Rate of capacitance change	Within ± 10.0%	Within ± 30.0%	Based on paragraph 9.10  Test temperature: Max. operating tem Applied voltage : rated voltage × 200  Test time : 1,000 to 1,048 hrs.	
	Dissipation factor ( $tan\delta$ )	5.0% or less	7.5% or less (when rated voltage is 16V: 10.0%)		
	Insulation resistance	1,000M $\Omega$ or 50M $\Omega$ · μF, whichever is smaller		Capacitance measured after 48 ± 4 hrs	

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#### Packaging specifications

(Units: mm)



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#### Electrical characteristics

### ■A (C0G) Characteristics

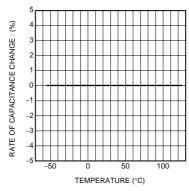


Fig.1 Capacitance-temperature characteristics

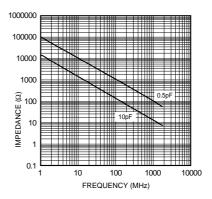


Fig.2 Impedance-frequency characteristics

#### ■ CN (X7R) Characteristics

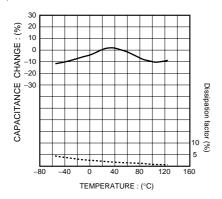


Fig.3 Capacitance-temperature characteristics

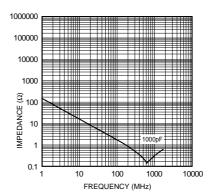


Fig.4 Impedance-frequency characteristics

#### ■FN (Y5V) Characteristics

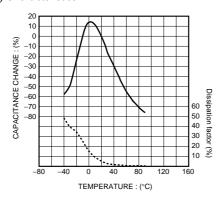


Fig.5 Capacitance-temperature characteristics

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